

# HEF4081B-Q100

## Quad 2-input AND gate

Rev. 1 — 13 November 2013

Product data sheet

### 1. General description

The HEF4081B-Q100 is a quad 2-input AND gate. The outputs are fully buffered for highest noise immunity and pattern insensitivity to output impedance variations.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

### 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Inputs and outputs are protected against electrostatic effects
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- Complies with JEDEC standard JESD 13-B

### 3. Ordering information

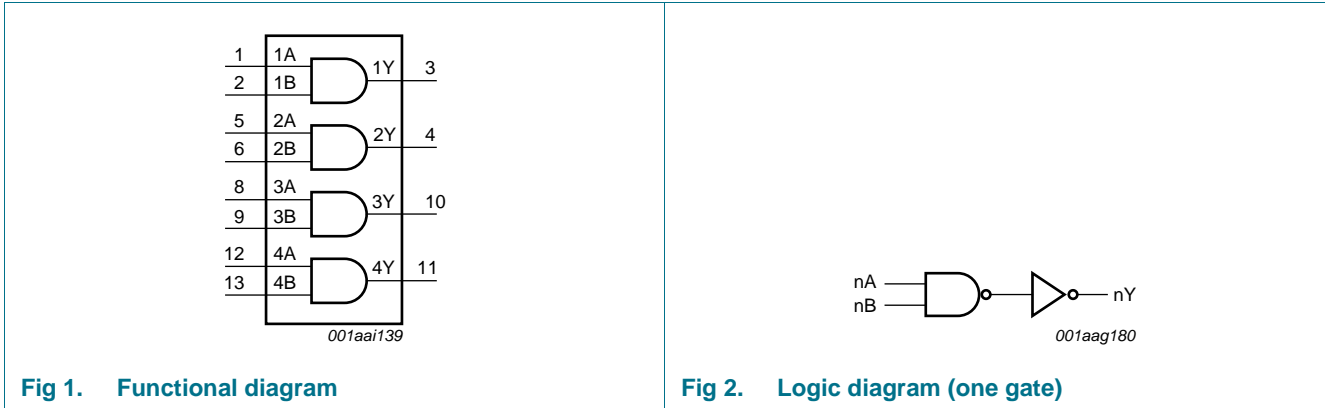
**Table 1. Ordering information**

All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$ .

Type number	Package		
	Name	Description	Version
HEF4081BT-Q100	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1

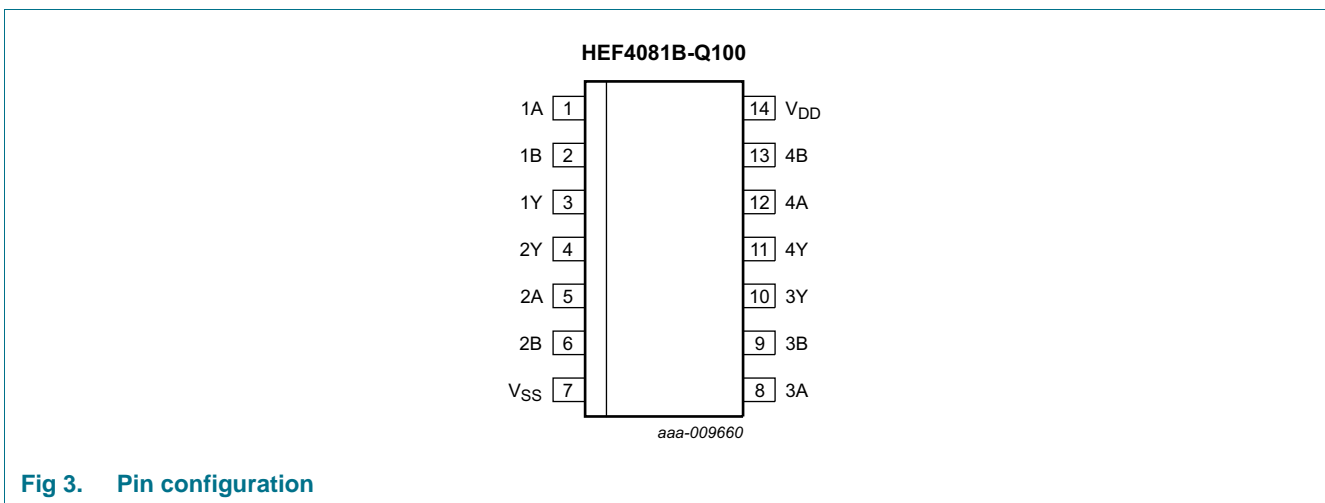


## 4. Functional diagram



## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

**Table 2. Pin description**

Symbol	Pin	Description
1A to 4A	1, 5, 8, 12	input
1B to 4B	2, 6, 9, 13	input
1Y to 4Y	3, 4, 10, 11	output
V <sub>SS</sub>	7	ground (0 V)
V <sub>DD</sub>	14	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input		Output
nA	nB	nY
L	L	L
L	H	L
H	L	L
H	H	H

[1] H = HIGH voltage level; L = LOW voltage level.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to  $V_{SS} = 0$  V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		-0.5	+18	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	$\pm 10$	mA
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	$\pm 10$	mA
$I_{I/O}$	input/output current		-	$\pm 10$	mA
$I_{DD}$	supply current		-	50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$T_{amb}$	ambient temperature		-40	+125	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to + 125 °C	<sup>[1]</sup> -	500	mW
P	power dissipation	per output	-	100	mW

[1] For SO14 packages: above  $T_{amb} = 70$  °C,  $P_{tot}$  derates linearly with 8 mW/K.

## 8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		3	15	V
$V_I$	input voltage		0	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10$ V	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15$ V	-	0.08	$\mu\text{s/V}$

## 9. Static characteristics

**Table 6. Static characteristics**

$V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ °C}$		$T_{amb} = +25\text{ °C}$		$T_{amb} = +85\text{ °C}$		$T_{amb} = +125\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mA
$I_I$	input leakage current		15 V	-	$\pm 0.1$	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	0.25	-	0.25	-	7.5	-	7.5	$\mu\text{A}$
			10 V	-	0.5	-	0.5	-	15.0	-	15.0	$\mu\text{A}$
			15 V	-	1.0	-	1.0	-	30.0	-	30.0	$\mu\text{A}$
$C_I$	input capacitance			-	-	-	7.5	-	-	-	pF	

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ; for waveforms see [Figure 4](#); for test circuit, see [Figure 5](#); unless otherwise specified. [1]

Symbol	Parameter	Conditions	V <sub>DD</sub>	Extrapolation formula	Min	Typ	Max	Unit
t <sub>PHL</sub>	HIGH to LOW propagation delay	nA or nB to nY	5 V	28 ns + (0.55 ns/pF)C <sub>L</sub>	-	55	110	ns
			10 V	14 ns + (0.23 ns/pF)C <sub>L</sub>	-	25	50	ns
			15 V	12 ns + (0.16 ns/pF)C <sub>L</sub>	-	20	40	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	nA or nB to nY	5 V	18 ns + (0.55 ns/pF)C <sub>L</sub>	-	45	90	ns
			10 V	9 ns + (0.23 ns/pF)C <sub>L</sub>	-	20	40	ns
			15 V	7 ns + (0.16 ns/pF)C <sub>L</sub>	-	15	30	ns
t <sub>THL</sub>	HIGH to LOW output transition time		5 V	10 ns + (1.0 ns/pF)C <sub>L</sub>	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C <sub>L</sub>	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C <sub>L</sub>	-	20	40	ns
t <sub>TLH</sub>	LOW to HIGH output transition time		5 V	10 ns + (1.00 ns/pF)C <sub>L</sub>	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C <sub>L</sub>	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C <sub>L</sub>	-	20	40	ns

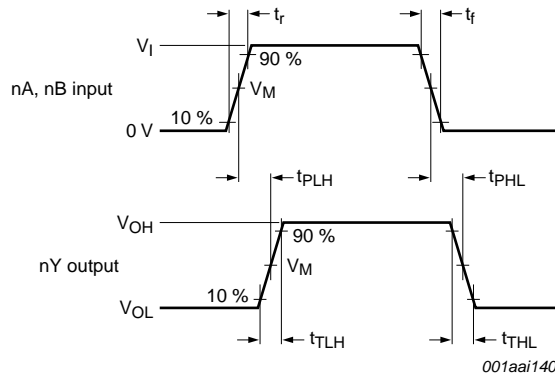
[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C<sub>L</sub> in pF).

**Table 8. Dynamic power dissipation**

$V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	V <sub>DD</sub>	Typical formula	where:
P <sub>D</sub>	dynamic power dissipation	5 V	$P_D = 450 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	f <sub>i</sub> = input frequency in MHz;
		10 V	$P_D = 2900 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	f <sub>o</sub> = output frequency in MHz;
		15 V	$P_D = 11700 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$ (μW)	C <sub>L</sub> = output load capacitance in pF; Σ(f <sub>o</sub> × C <sub>L</sub> ) = sum of the outputs; V <sub>DD</sub> = supply voltage in V.

11. Waveforms

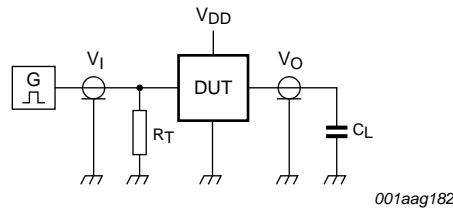


Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Fig 4. Input to output propagation delay and output transition times

Table 9. Measurement points

Supply voltage	Input	Output
$V_{DD}$	$V_M$	$V_M$
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$



Test data is given in [Table 10](#).  
 Definitions for test circuit:  
 DUT = Device Under Test.  
 $C_L$  = load capacitance including jig and probe capacitance.  
 $R_T$  = termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

Fig 5. Test circuit

Table 10. Test data

Supply voltage	Input		Load
$V_{DD}$	$V_I$	$t_r, t_f$	$C_L$
5 V to 15 V	$V_{SS}$ or $V_{DD}$	$\leq 20$ ns	50 pF

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

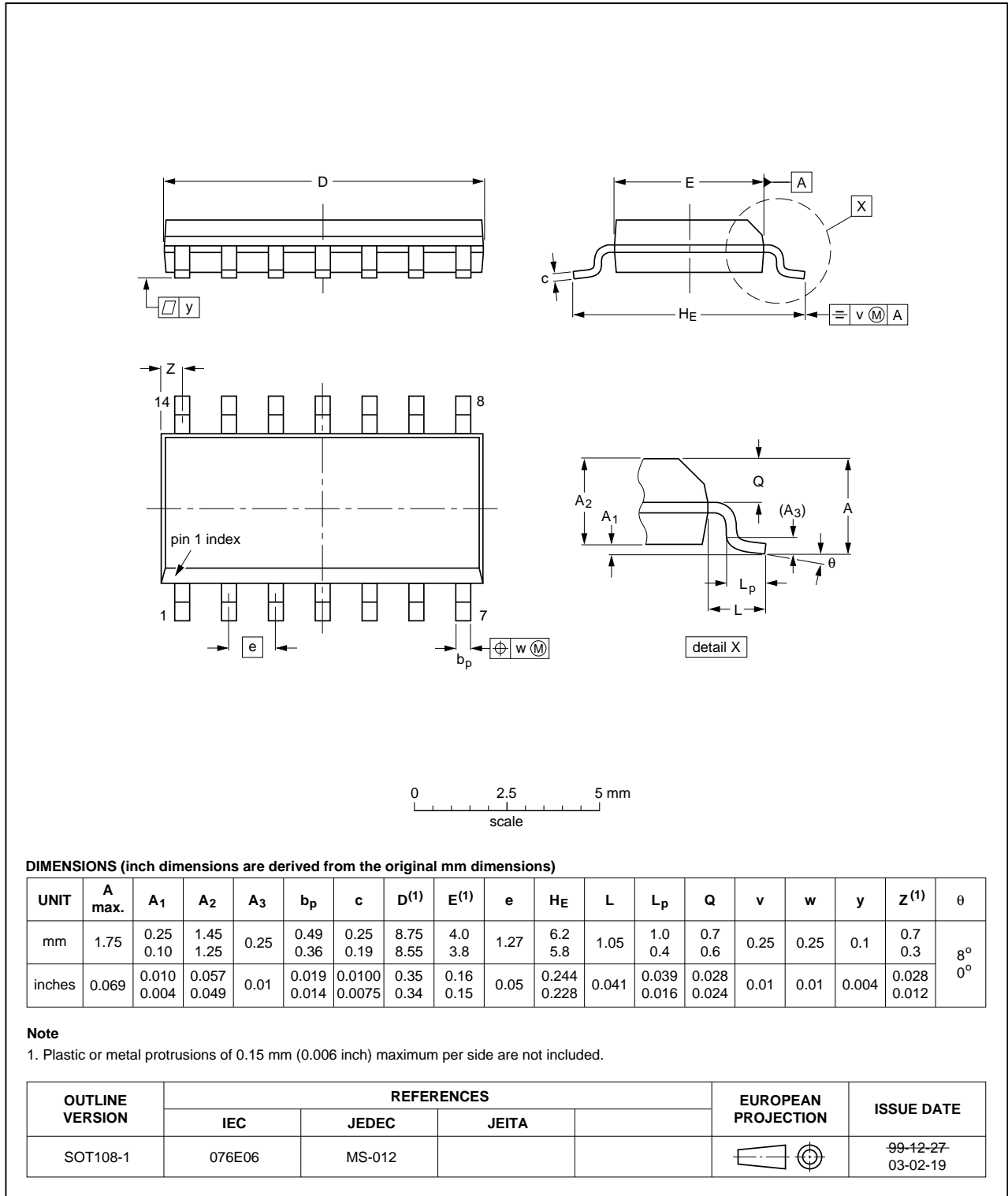


Fig 6. Package outline SOT108-1 (SO14)

## 13. Abbreviations

Table 11. Abbreviations

Acronym	Description
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
MIL	Military

## 14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4081B_Q100 v.1	20131113	Product data sheet	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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